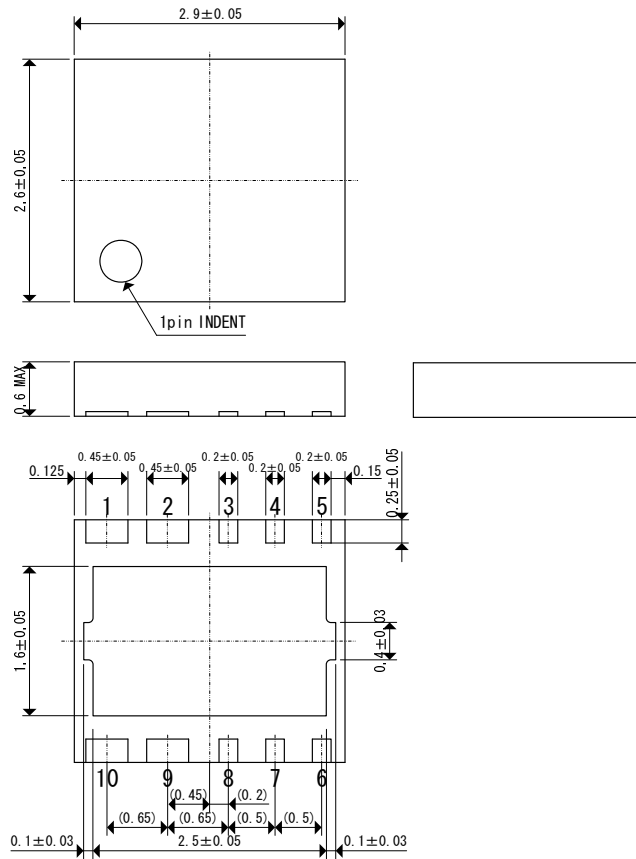


# Packaging Information / Reference Pattern Layout Dimensions

● USP-10B

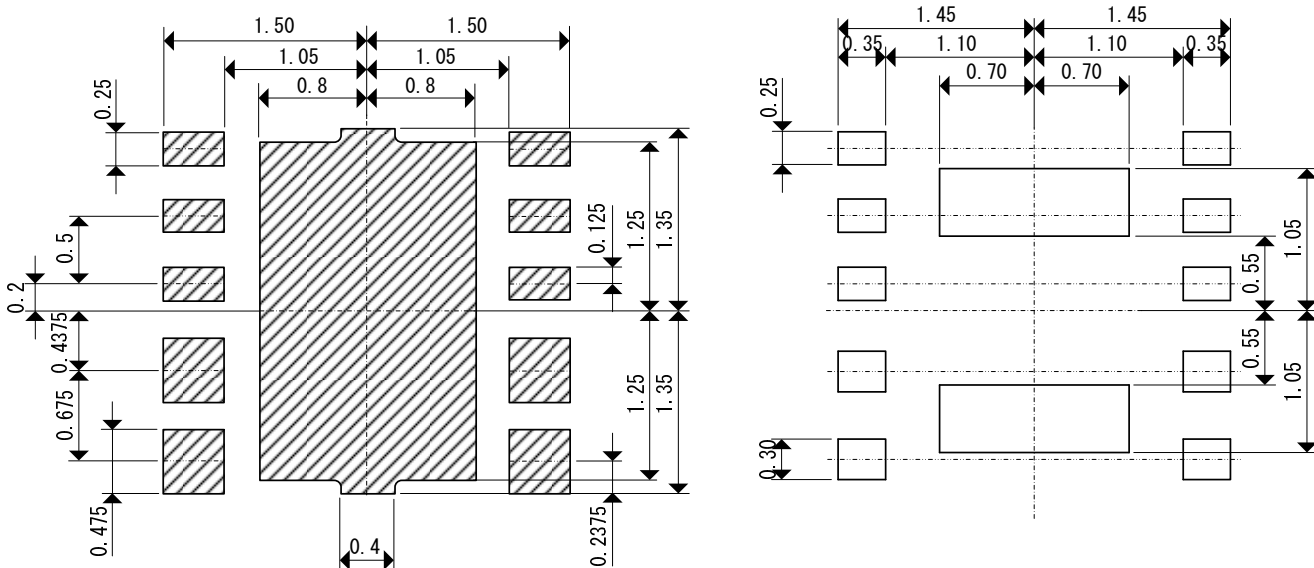
Unit: mm

## ■ Packaging Information



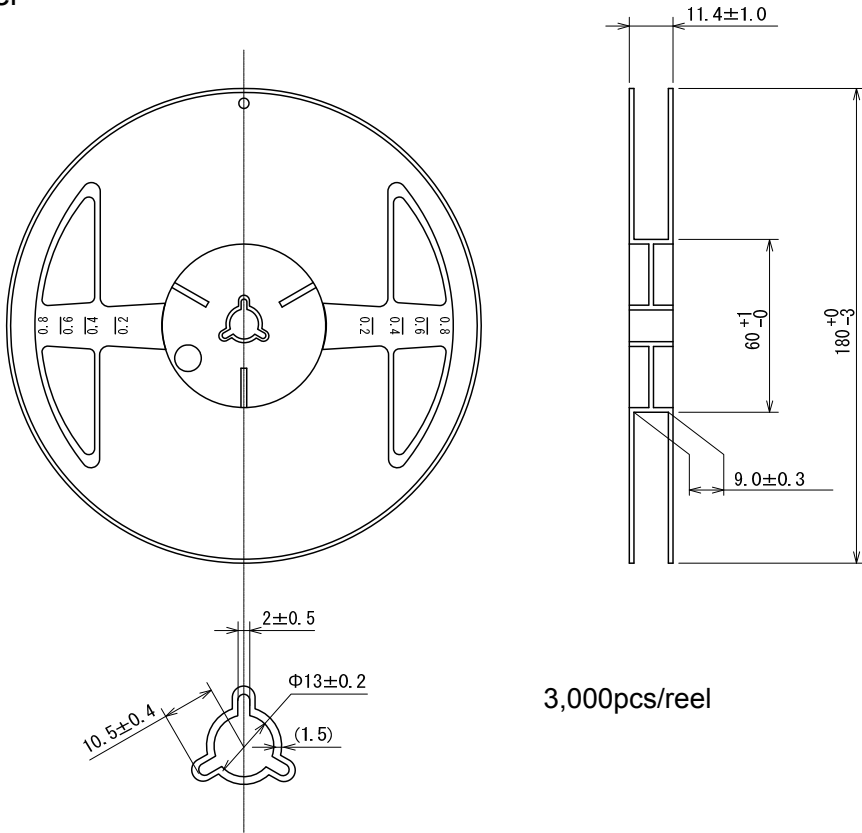
## ■ Reference Pattern Layout Dimension

Note : reference metal mask design



# Taping Specifications

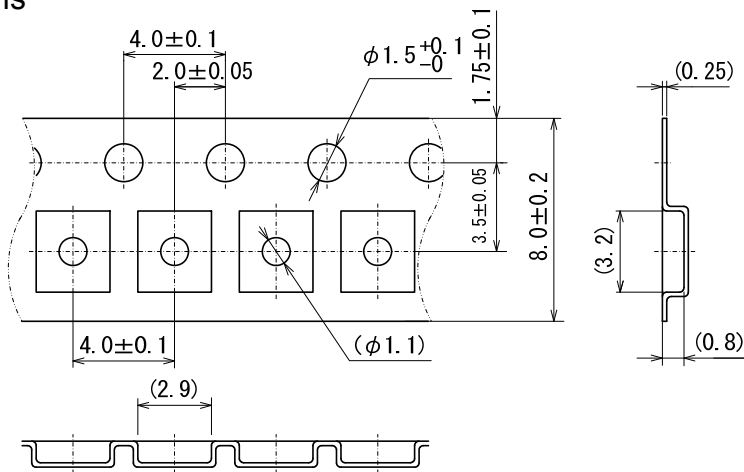
●USP-10B Reel



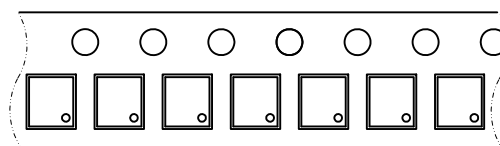
Unit: mm

3,000pcs/reel

●Taping Specifications



direction of feed



R Type :[Device orientation : Right]

Standard feed

**●USP-10B Power Dissipation**

Power dissipation data for the USP-10B is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

**1. Measurement Condition (Reference data)**

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

Board : Dimensions 40mm×40mm (1600mm<sup>2</sup> in one side)

1st Inner Metal Layer about 50%

2nd Inner Metal Layer does not exist

3rd Inner Metal Layer does not exist

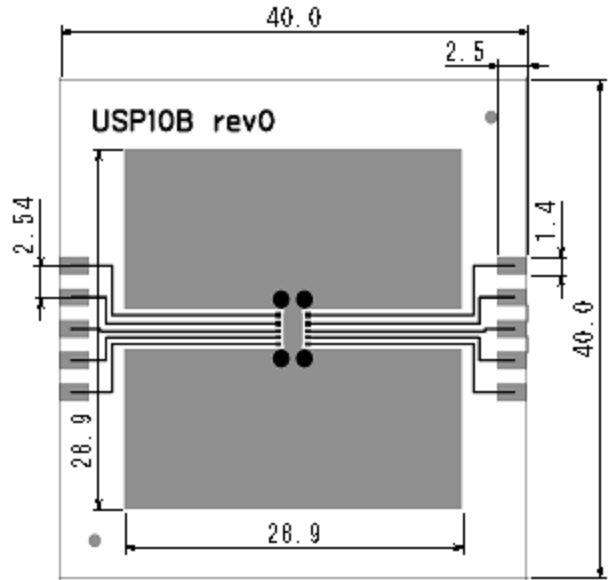
4th Inner Metal Layer about 50%

Each heat sink back metal is connected to the Inner layers respectively.

Material : Glass Epoxy (FR-4)

Thickness : 1.6mm

Through-hole : 4 x 0.8 Diameter

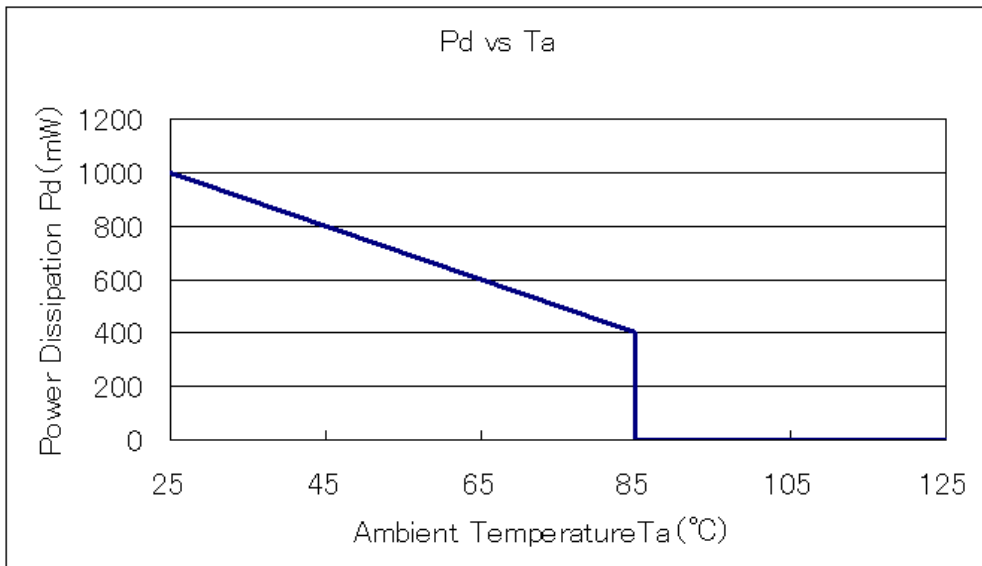


Evaluation Board (Unit: mm)

**2. Power Dissipation vs. Ambient temperature**

Board Mount ( Tjmax=125°C)

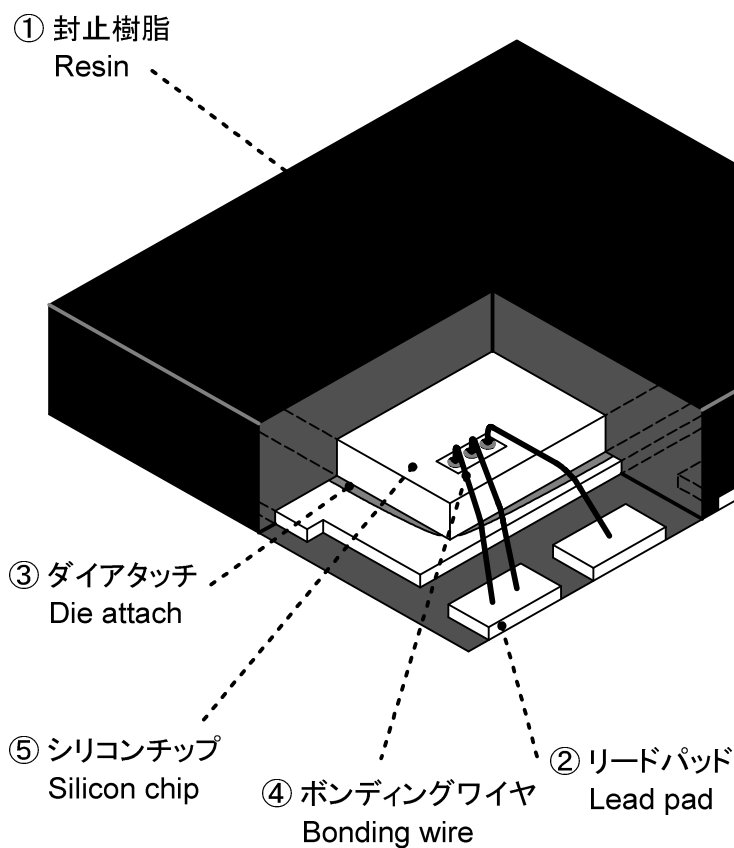
Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1000	100.00
85	400	



## USP-10B 構造図

### USP-10B Perspective

RoHS対応品  
RoHS Compliance



項目 Item	材料 Material	備考 Note
① 封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
② リードパッド Lead pad	ニッケル Nickel	端子側面は除く Except the side of the terminals.
端子処理 Outer pad plating	Auメッキ Gold plating	
③ ダイアタッチ Die attach	エポキシ Epoxy	
④ ボンディングワイヤ Bonding wire	Au	
⑤ シリコンチップ Silicon chip	Si	

捺印表示 Marking	レーザー Laser marking
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